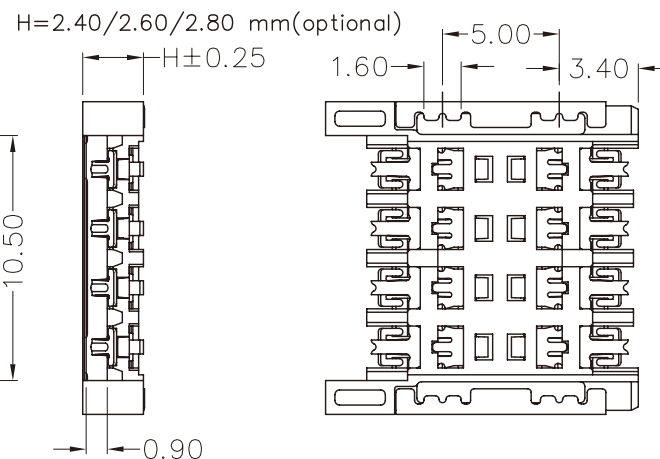
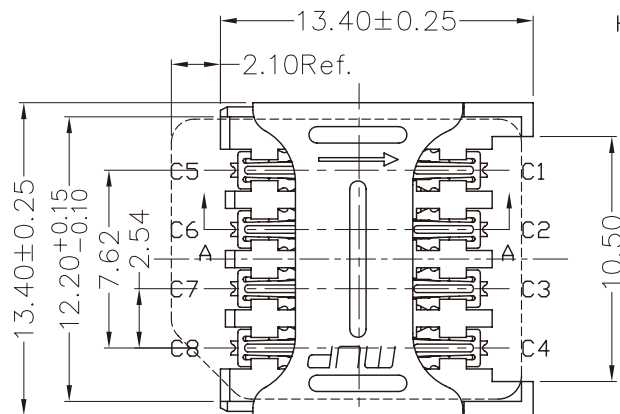


TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 13.40LX13.40WX2.40/2.60/2.80H mm

Weight: Approx0.50±0.1g

Durability:5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C,30sec.Max

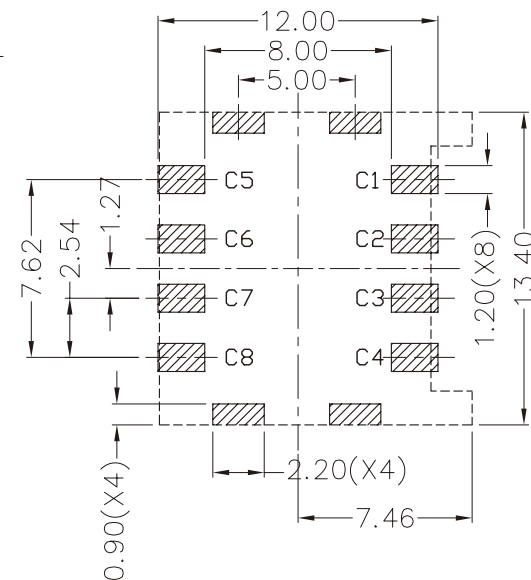
IR reflow: 250°C,5sec.Max

Manual soldering: 370°C,3sec.Max

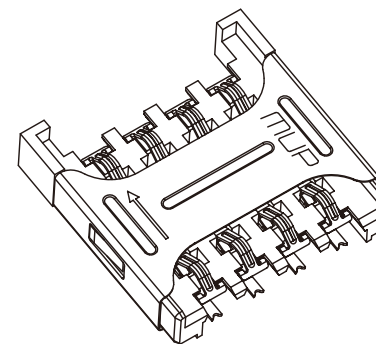
4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6/8	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless steel	SMT area:Gold plated

RoHS Compliant

TOLERANCES ARE

MORETHANALL
PCB CONNECTORS
Cable ASSEMBLIES

煜倫股份有限公司

www.morethanall.com

DRAWING BY CY

CHECKED BY GENIUS

UNIT / mm

SCALE 1:1

DATE

SIZE A4

X. ± 0.35

.X ± 0.25

.XX ± 0.15

.XXX ± 0.10

ANG ±

PPOJECTION

照片框

ORDER INFORMATION

MISCT-W10xxX-08-LF

SERIES

LEADFREE

08 WAY

NON POST

90°SMT

PAD TO PAD 10.0mm

24:HIGH 2.4mm

26:HIGH 2.6mm

28:HIGH 2.8mm

DESCRIPTION: **Micro-SIM Card Connector**